

1. Scope :

This specification applies to silicon zener double diodes chips,
Device NO. SD-51513GN-A

2. Structure :

- 2-1. Planar type : PNP, Zener Double Diodes.
- 2-2. Electrodes :
Top side : Au pads.

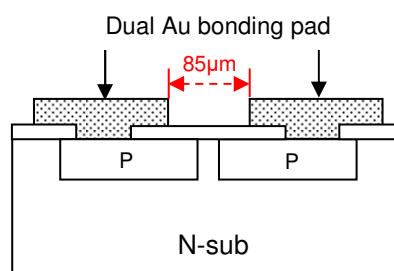
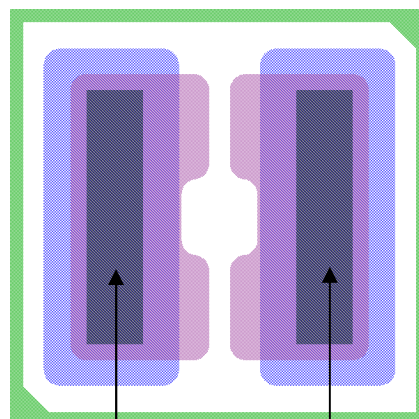
3. Size :

- 3-1. *Chip size : 15.6 mils x 15.6 mils (0.395 mm x 0.395 mm).
- 3-2. Chip thickness : 5.9 ± 1.0 mils (0.150 ± 0.025 mm)
- 3-3. Bonding pad : 12.2mils x 4.7 mils (0.310 mm x 0.120 mm).
- 3-4. The distance between dual Au bonding pad: 3.3mils (0.085 mm).
- 3-5. Pattern drawing : Refer to the attached drawing.

*Including scribing line. The chip size is about $(0.370 \pm 0.015) \times (0.370 \pm 0.015)$ mm² after dicing.

4. Electrical characteristics (Ta = 25 °C)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Reverse Leakage Current	I _R	V _R =9V E _e =0mW/cm ²			100	nA
Zener Voltage	V _Z	I _Z =5mA E _e =0mW/cm ²	11		15	V



Equivalent Circuit

